



Blockchain and Edge Computing Techniques for Emerging IoT Applications

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Message from the Guest Editors

Dear Colleagues,

As number of Internet connected devices is dramatically increasing, IoT is getting more prevalent for emerging applications to meet the demands of efficient, flexible, reliable and powerful accessibility of cyberspace from physical systems. More devices are concerned with offering an innovative approach to quality of life, urban challenges, food production, agriculture, manufacturing, medicine, energy supply, and how to offer a wide variety of smart products and services.

The motivation of this special issue is to discover and promote the current advancements, techniques, innovation, and real-world solutions of blockchain and edge computing techniques in IoT infrastructure. This special issue will focus on gathering both quantitative and qualitative research contributions from individual, academic, organizational and industry practitioners in the newly emerging area of blockchain and edge computing solutions for resource management, scalable operation, big data processing, and dependability issues in IoT.





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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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